

# **A SEMICONDUCTOR DEVICE WITH A PLURALITY OF GROUND PLANES**

Fan Ho

## **ABSTRACT**

[0037] A multi-chip module (MCM) with a plurality of ground planes/layers is provided. Each integrated circuit (IC) chip of the MCM has its own ground plane on a substrate in the MCM. This MCM structure may facilitate separate testing of each IC chip without affecting other chips and without being affected by other chips. This MCM structure also may facilitate testing of interconnects/connections between two or more chips.